

it enclosures INC.™

SUPERIOR ELECTRONICS PACKAGING SOLUTIONS

CENTRAL OFFICE...EARTH STATION xDSL

CPCI...CDMA/TDMA...MIL-SPEC

VSAT

EMBEDDED SYSTEMS

IP telephony...Wireless

C³I

computer telephony

CPCI...VEHICULAR...TACTICAL...AIRBORNE

VME...UL/ETSI/CE/NEBS compliance

E-LINT...ATM...VXI

E-LINT...ATM...VXI

IP TELEPHONY

ATM

To build today's complex systems...

rackit™

Compact PCI, VME, and custom 19-inch subrack enclosures

Turn-key subracks suitable for housing open-system bus architecture electronic modules for commercial, high reliability or severe environment applications, meets CE/NEBS compliance requirements

coolit™

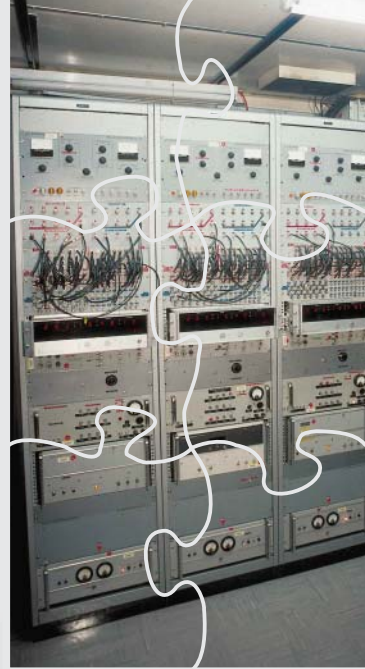
High performance, redundant, hot-swappable, and modular thermal management units for high impedance and high power density applications; available in AC or DC input versions

Units provide high reliability thermal management for power dissipations from 100 W to 1.5 kW; designed to mate with all **rackit** and **alarmit** products

busit™

High performance, standard or custom backplane systems for all popular open-system bus architectures

IT Enclosures develops, simulates, and manufactures a wide range of backplane solutions for high speed data, voice, and computer telephony applications. These solutions are implemented using standard, open systems, hybrid or custom bus technologies.



alarmit™

Compact PCI 6U x 80mm transition module that enables monitoring of 2 alarm inputs and 2 outputs, temperature, and power

Module is designed to be user configurable and mates with **rackit**, **powerit**, **busit**, and **coolit** products to provide system alarm functions.

customizeit™

IT provides custom electronic packaging solutions for those special applications in industrial/commercial ground, aerospace, and hostile environments that cannot be achieved with standard products

Custom system development capabilities for enclosures and complex electronic systems:

- thermal analysis
- stress analysis
- bus architecture simulation
- system layout and circuit design
- detailed part design
- power system development and analysis

powerit™

Compact PCI, and VME plug-in power supply modules for high power commercial or ruggedized environments

Cost-effective high power (250–2kW) solutions for AC/DC input and multi-voltage DC outputs in a 1:1 or N:1 redundant application. Supplies are designed to mate with all **rackit** and **alarmit** products

pakit™








Dozens of plastic molded electronic enclosures for single broad commercial applications

Use an off-the-shelf molded case to give your product that professional look—cases can be made with custom colors and logos

...You need the right pieces

Product Line Summary

For product specifications, download information at: www.ITenclosures.com

Product Group	Description	Model	Compliance
	3U CPCI subracks, with or without transition modules	5001 Series	CPCI-PICMG 2.0 R2.1 Dimensions of mechanical structures (19-inch)-IEC-297-3 Mechanical specifications for micro computers-IEEE 1101.10-1996 and IEEE 1101.1-1991
	6U CPCI subracks, with or without transition modules	5021 Series	
	Redundant, impeller-based thermal management units for 1U, 2U, and 3U rack applications—to 1000W dissipation	5100 Series	Dimensions of mechanical structures (19-inch)-IEC-297-3 Mechanical specifications for micro computers-IEEE 1101.10-1996 and IEEE 1101.1-1991
	VME, CPCI, and custom backplanes for 3U, 6U, and 9U hot-swap and redundant applications	5300 Series	CPCI-PICMG 2.0 R2.1 Versatile back-plane bus, VME bus-IEEE 1014-1987 Dimensions of mechanical structures (19-inch)-IEC-297-3 Mechanical specifications for micro computers-IEEE 1101.10-1996 and IEEE 1101.1-1991
	CPCI and VME plug-in power supply units for 3U and 6U applications requiring 1:1 or N:1 redundant operation—to 2 kW	5200 Series	CPCI-PICMG 2.0 R2.1 Dimensions of mechanical structures (19-inch)-IEC-297-3 Mechanical specifications for micro computers-IEEE 1101.10-1996 and IEEE 1101.1-1991
	CPCI 6U transition size alarm interface modules—user configurable	5500 Series	CPCI-PICMG 2.0 R2.1 Dimensions of mechanical structures (19-inch)-IEC-297-3 Mechanical specifications for micro computers-IEEE 1101.10-1996 and IEEE 1101.1-1991
	A wide variety of plastic molded enclosures for consumer industrial applications	0400 Series	Flame retardant-UL94V0 (ABS plastic)
	Custom system development capabilities for enclosures and complex electronic systems: <ul style="list-style-type: none">• thermal analysis• stress analysis• bus architecture simulation• system layout• detail part design• power system development and analysis		All applicable specifications (above) Environmental test methods: engineering guidelines-MIL-STD-810 Electromagnetic emissions-MIL-STD-461 Mechanical vibrations-MIL-STD-167 (shipboard) Light, medium, heavy duty hammer shock-MIL-STD-901



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